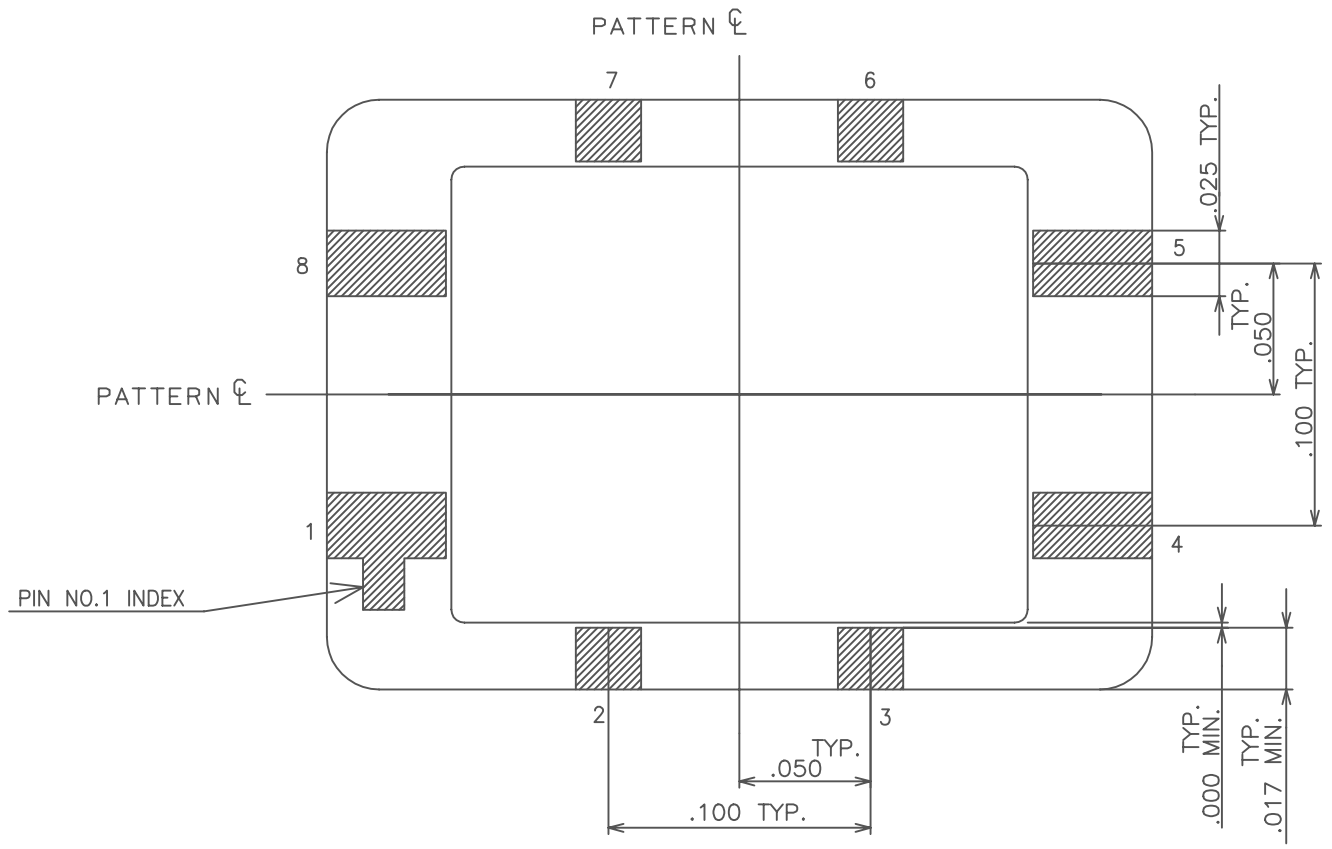


- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. LEAD RESISTANCE : 0.20Ω MAX.
  3. SEAL AREA TO BE METALLIZED.
  4. DIE ATTACH AREA TO BE NOT METALLIZED.
  5. SEAL RING AREA TO BE FLOATING FROM ANY PINS.

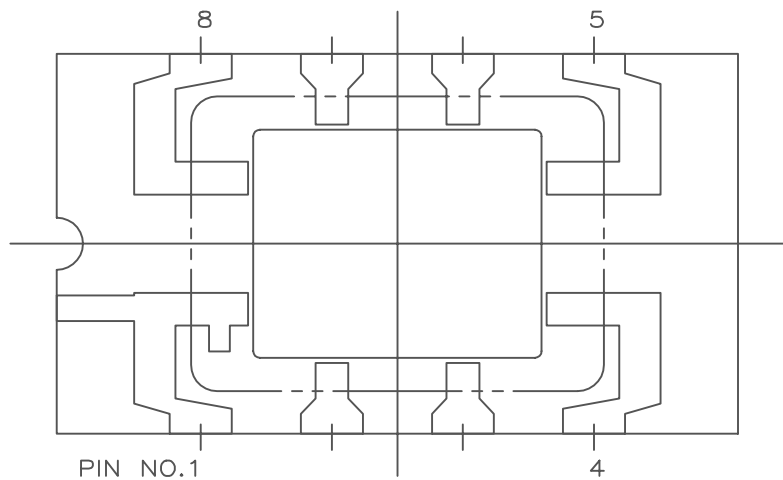
SB008AD083-1 S=0 D=N

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.SU	H.S	T.A	FEB.3.'95
						SCALE 8/1	MATERIAL AS INDICATED		S.F		
							±.005				
						THIRD ANGLE PROJECTION					
	CHANGED		DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
								KD-S95083		1/3	



BONDING PATTERN

MODIFICATION					NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
					8 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	M.SU	H.S.	T.A	FEB.3.'95
					SCALE 20/1	MATERIAL		S.F		
						THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
							KD-S95083		2/3	



SECOND LAYER PATTERN

MODIFICATIONS

CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME	8 LEAD SIDE BRAZED PACKAGE
SCALE	10 / 1
MATERIAL	
<b>KYOCERA</b>	

TOLERANCES: UNLESS OTHERWISE SPECIFIED	
THIRD ANGLE PROJECTION	

DRAWN	CHECKED	APPROVED	DATE
M.SU	H.S. S.F	T.A	FEB.3.'95
DRAWING NO.			SHEET
KD-S95083			3 / 3

KYOCERA CORPORATION  
KYOTO JAPAN